

What is claimed is:

1. An assembly comprising an electronic device; and a multilayer film, the multilayer film comprising:
 - a substrate adjacent the electronic device;
 - a barrier stack adjacent the substrate opposite the electronic device; and
 - a polymer weatherable sheet adjacent the barrier stack opposite the substrate,wherein the multilayer film has been fused.
2. The assembly of claim 1 wherein the barrier stack comprises a polymer layer and an inorganic barrier layer.
3. The assembly of claim 2 wherein the inorganic barrier layer is an oxide layer.
4. The assembly of claim 1 wherein the multilayer film is transparent and flexible
5. The assembly of claim 1 wherein the weatherable sheet and the substrate are fused.
6. The assembly of claim 1 wherein the barrier stack is between the weatherable sheet and the substrate at the point of fusion.
7. The assembly of claim 1 wherein the edge has been ultrasonically welded.
8. The assembly of claim 1 wherein the edge has been laser fused.
9. The assembly of claim 1 wherein the electronic device comprises an edge seal material.
- ~~10. The assembly of claim 1 wherein the electronic device comprises a backsheet.~~
- ~~11~~10. The assembly of claim 1 wherein the electronic device comprises an encapsulant layer.
- ~~12~~11. The assembly of claim 9 wherein the edge seal material comprises butyl rubber.
- ~~13~~12. The assembly of claim 1 wherein the weatherable sheet is fused to the electronic device.
- ~~14~~13. The assembly of claim 1 wherein the substrate comprises at least one of polyethylene terephthalate, polyethylene naphthalate, polyetheretherketone, polyaryletherketone, polyacrylate, polyetherimide, polyarylsulfone, polyethersulfone, polyamideimide, or polyimide.
- ~~15~~14. The assembly of claim 1 wherein the weatherable sheet comprises a fluoropolymer.

~~16~~15. The assembly of claim ~~15~~14 wherein the fluoropolymer comprises at least one of an ethylene tetrafluoro-ethylene copolymer, a tetrafluoroethylene-hexafluoropropylene copolymer, a tetrafluoroethylene-hexafluoropropylene-vinylidene fluoride copolymer, or a polyvinylidene fluoride.

~~17~~16. The assembly of claim 1 comprising a pressure sensitive adhesive layer between the weatherable sheet and the barrier stack.

~~18~~17. The assembly of claim ~~17~~16 wherein the pressure sensitive adhesive is an acrylate, a silicone, a polyisobutylene, a urea or a blend thereof.

~~19~~18. The assembly of claim ~~17~~16 wherein the pressure sensitive adhesive comprises at least one of a UV stabilizer, a hindered amine light stabilizer, an antioxidant or a thermal stabilizer.

~~20~~19. The assembly of claim 1 wherein the barrier stack oxide layer shares a siloxane bond with the barrier stack polymer layer.

~~21~~20. The assembly of claim 1 wherein the electronic device is a photovoltaic cell.

~~22~~21. The assembly of claim ~~21~~20 wherein the photovoltaic cell is a CIGS cell.

~~23~~22. The assembly of claim 1 wherein the substrate is heat stabilized.

~~24~~23. The assembly of claim 1 wherein the barrier stack has a water vapor transmission rate of less than 0.005 cc/m²/day at 50°C and 100% relative humidity.

~~25~~24. The assembly of claim 1 wherein the barrier stack has an oxygen transmission rate of less than 0.005 cc/m²/day at 23°C and 90% relative humidity.

~~26. The assembly of claim 1 wherein the barrier stack comprises at least two oxide layers.~~

~~27. The assembly of claim 1 wherein the barrier stack comprises at least two polymers layers.~~

~~28. The assembly of claim 1 wherein the electronic device comprises a roof.~~

~~29~~25. The assembly of claim 1 wherein the multilayer film has been fused around a perimeter of the assembly.